Claims

1. An electronic package, comprising:

a substrate;

an electronic component mounted to a surface of the substrate;

an interposer mounted to the surface of the substrate such that the interposer surrounds the electronic component and is electrically connected to the substrate; and

an over-mold that covers the electronic component.

2. The electronic package of claim 1, wherein the substrate is a motherboard.

3. The electronic package of claim 1, wherein the interposer is organic polymers, fibers and conductors.

4. The electronic package of claim 1, wherein the over-mold is a polymer.

5. The electronic package of claim 1, wherein the over-mold fills an area between the electronic component and the interposer.

6. The electronic package of claim 5, wherein the over-mold fills the area between the interposer and the substrate.

7. The electronic package of claim 5, wherein the over-mold fills the area between the interposer and the substrate.

8. The electronic package of claim 1, wherein the interposer is mounted to the substrate using solder bumps.

9. The electronic package of claim 1, further comprising solder bumps mounted to an opposing surface of the substrate.

10. An electronic assembly, comprising:

a substrate;

an first electronic component mounted to a surface of the substrate;

an interposer mounted to the surface of the substrate such that the interposer surrounds the electronic component and is electrically connected to the substrate;

an over-mold that covers the electronic component; and

a second electronic component mounted to the interposer.

11. The electronic assembly of claim 10, wherein the second electronic component is mounted to the interposer using solder bumps.

12. The electronic assembly of claim 10, wherein the second electronic component is electrically connected to the substrate through the interposer.

13. The electronic assembly of claim 10, wherein the second electronic component is a DRAM.

14. A method of fabricating an electronic package, the method comprising:

attaching an electronic component to a surface of a substrate;

attaching an interposer to the surface of the substrate such that the interposer surrounds the electronic component; and

covering the electronic component with an over-mold.

15. The method of claim 14, wherein attaching an interposer to the surface of the substrate includes attaching the interposer to the substrate with solder bumps.

16. The method of claim 14, wherein covering the electronic component with an over-mold includes filling in an area between the electronic component and the interposer.

17. The method of claim 16, wherein covering the electronic component with an over-mold includes filling in an area between the substrate and the interposer.

18. A method of fabricating an electronic assembly, the method comprising:

attaching a first electronic component to a surface of a substrate;

attaching an interposer to the surface of the substrate such that the interposer surrounds the electronic component;

covering the first electronic component with an over-mold; and

attaching a second electronic component to the interposer.

19. The method of claim 18, wherein attaching a second electronic component to the interposer includes attaching a DRAM to the interposer using solder bumps.

20. The method of claim 18, wherein covering the first electronic component with an over-mold includes filling in a first area between a die and the interposer and filling in a second area between the interposer and the substrate.